Global OSAT Market with Focus on IC Packaging: Size, Trends & Forecasts (2018-2022)

August 2018

Daedal Research

Global OSAT Market: Coverage

- Executive Summary and Scope
- Introduction/Market Overview
- Global Market Analysis
- China Market Analysis
- Dynamics
- Competitive Landscape
- Company Profiling

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Global OSAT Market: Coverage

Scope of the Report

Attributes	Details
Title	Global OSAT Market with Focus on IC Packaging: Size, Trends & Forecasts (2018-2022)
Coverage	Global and Regional
Regional Coverage	China
Market Influencing Variables	Growth Drivers, Challenges, Market Trends
Forecast Period of Market	2018-2022
Competition in the Market	Dominated
Key Players	Advanced Semiconductor Engineering, (ASE) Inc., Amkor Technology, Inc., ChipMOS Technologies Inc. (ChipMOS), Mubadala Investment Company (GlobalFoundries Inc.)

Global OSAT Market

Executive Summary

An Integrated Circuit (IC) is defined as the circuit that is comprised of inseparable and electrically interconnected elements. An IC is basically a semiconductor wafer in which millions of components, like, tiny resistors, capacitors, and transistors, are fabricated.

ICs have distinct characteristics like, they are very small in size, have less weight, require low power, and are highly reliable, etc.

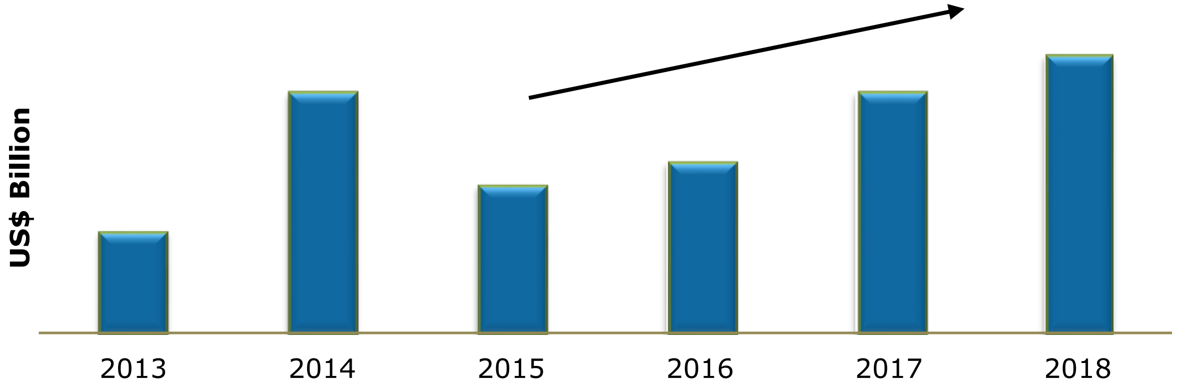
The OSATs offer Integrated Circuit packaging services on the open market to the integrated semiconductor manufacturers (ISMs), and fabless companies, and to IDMs and foundries as well. Outsourced Semiconductor Assembly and Test (OSAT) provide third-party Integrated Circuit (IC) packaging and test services.

The OSAT market can be segmented on the basis of technology used in IC packaging. OSAT is based on three major IC packaging technologies, named as Wirebond Packaging, Flip Chip Packaging and Wafer level Packaging.

The global OSAT market with focus on IC packaging has increased at a significant CAGR over the years and projections are made that the market would rise in the next four years i.e. 2018-2022 tremendously. The OSAT market is expected to increase due to rising automotive production, rising Internet of Things (IoT), growing personal electronics, increasing smartphone users, rising urban population etc. Yet the market faces some challenges such as volatile demand from cryptocurrency, etc.

OSAT Market: Global Analysis

Global OSAT Market by Value



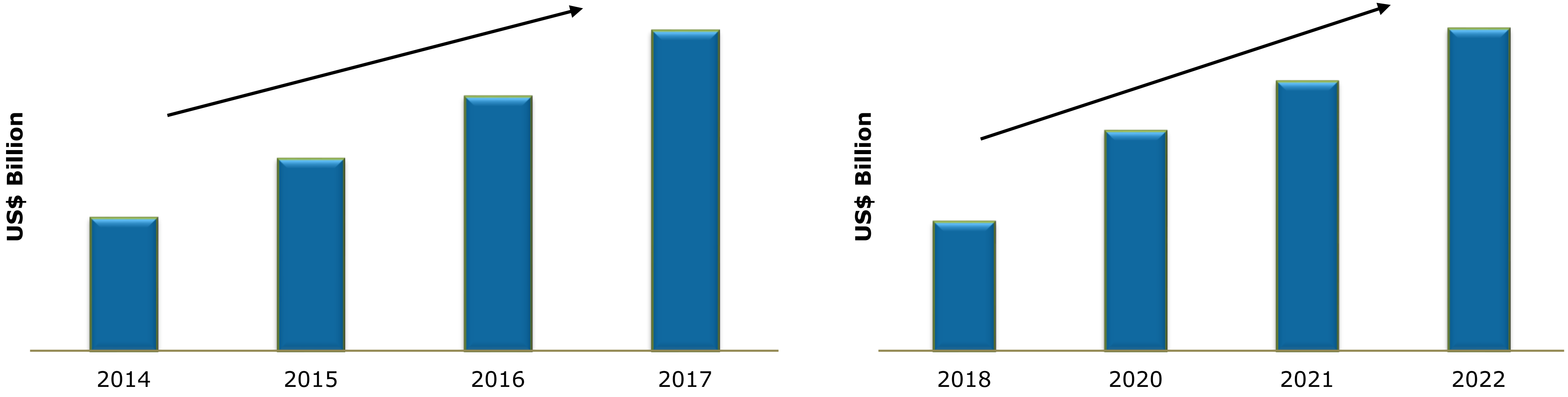
CAGRs	
2013-2018	xx%

Global OSAT Market by Region; 2017

Region	Share
China	xx%
Rest of World	xx%

IC Packaging Market: Global Analysis

Global IC Packaging Market by Value

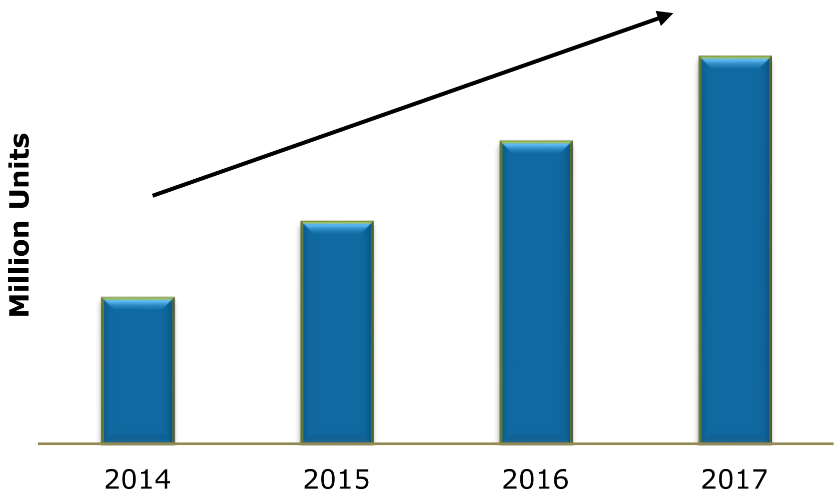


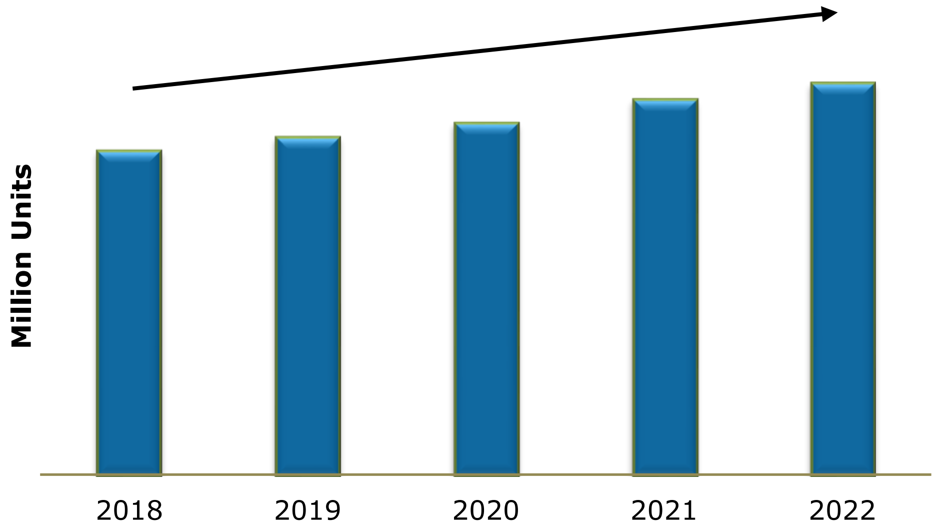
CAGRs	
2014-2017	xx%
2018-2022	xx%

The global IC Packaging market, valued at US$.... billion in 2017, increased as compared to US$... billion in 2016 at a CAGR of ….% from 2014 to 2017. The global IC Packaging market is anticipated to reach up to US$... billion by 2022 from US$... billion in 2018.

IC Packaging Market: Global Analysis

Global IC Packaging Market by Volume





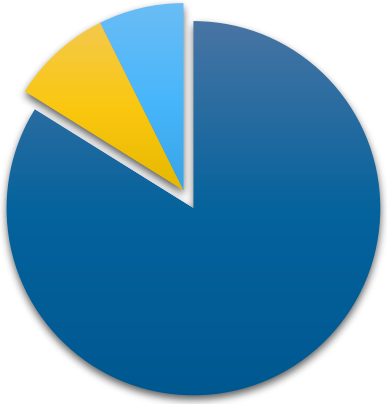
CAGRs	
2014-2017	xx%
2018-2022	xx%

The global IC Packaging market volume was .... million units in 2017, increased as compared to ... million units in 2016 at a CAGR of ….% from 2014 to 2017. The global IC Packaging market is anticipated to reach up to … million units by 2022 from ... million units in 2018.

IC Packaging Market: Global Analysis

Global IC Packaging Market by Segment; 2017

Global IC Packaging Market Volume by Segment; 2017



Segments	Share	Volume Share	CAGRs
Wirebond Packaging	xx%	xx%	xx%
Flip Chip Packaging	xx%	xx%	xx%
Wafer Level Packaging	xx%	xx%	xx%

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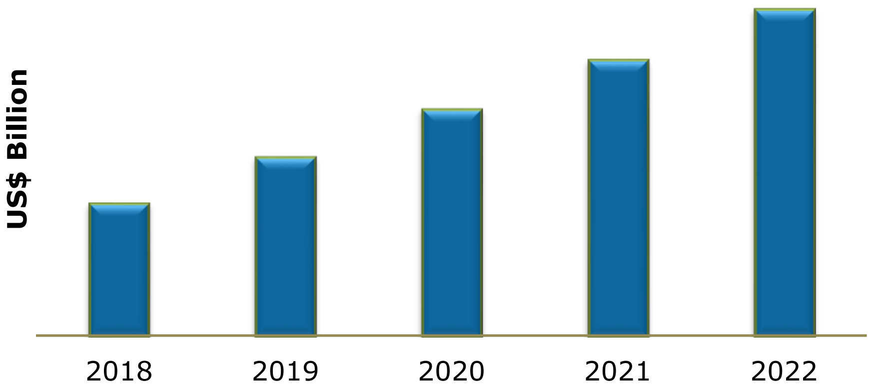
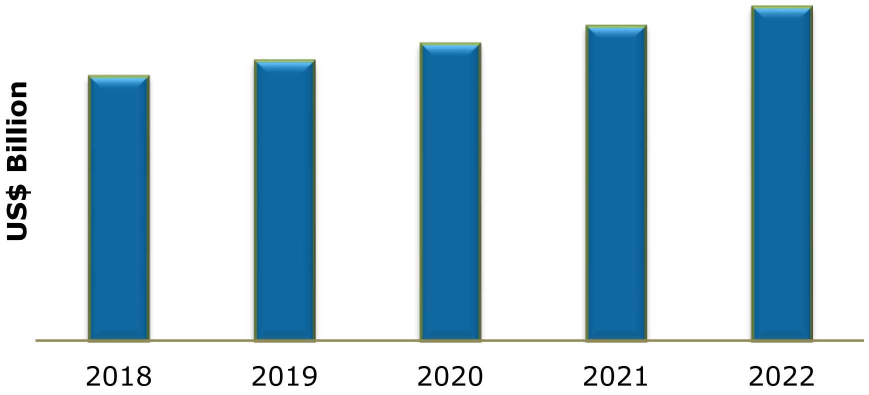
IC Packaging Market: Segment Analysis

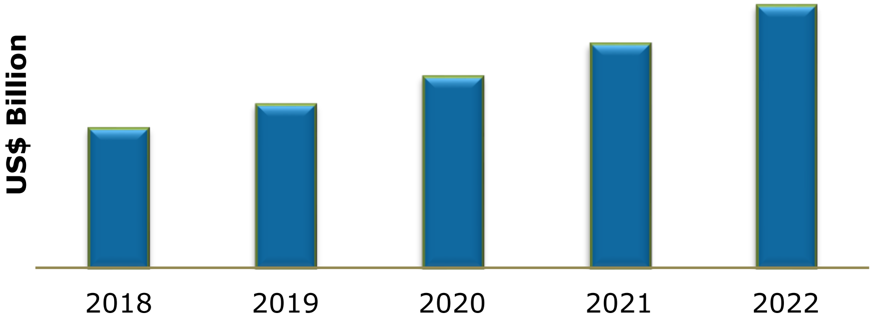
Global Wirebond (WB) Packaging Market by Value



Global Flip Chip (FC) Packaging Market by Value



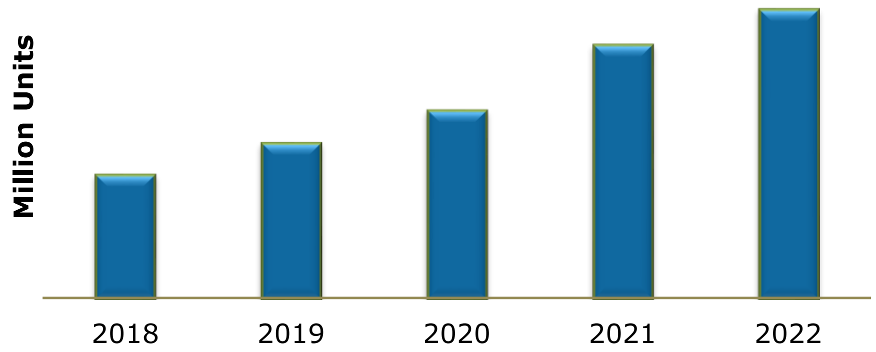
Global Wafer Level Packaging (WLP) Market by Value



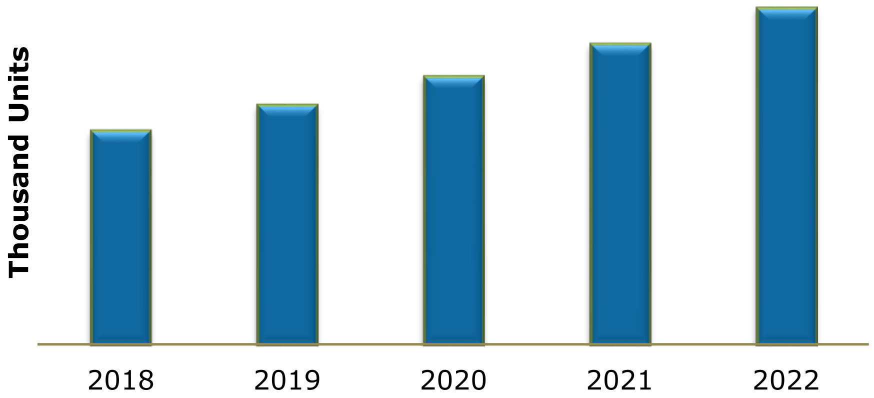
Segments	CAGR	
	2014-2017	2018-2022
Wirebond Packaging	xx%	xx%
Flip Chip Packaging	xx%	xx%
Wafer Level Packaging	xx%	xx%

IC Packaging Market: Segment Analysis

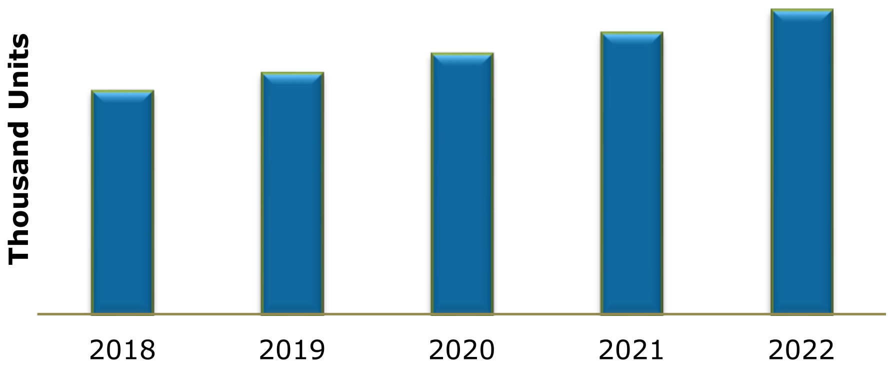
Global Wirebond (WB) Packaging Market by Volume



Global Flip Chip (FC) Packaging Market by Volume



Global Wafer Level Packaging (WLP) Market by Volume



Segments	CAGR	
	2014-2017	2018-2022
Wirebond Packaging	xx%	xx%
Flip Chip Packaging	xx%	xx%
Wafer Level Packaging	xx%	xx%

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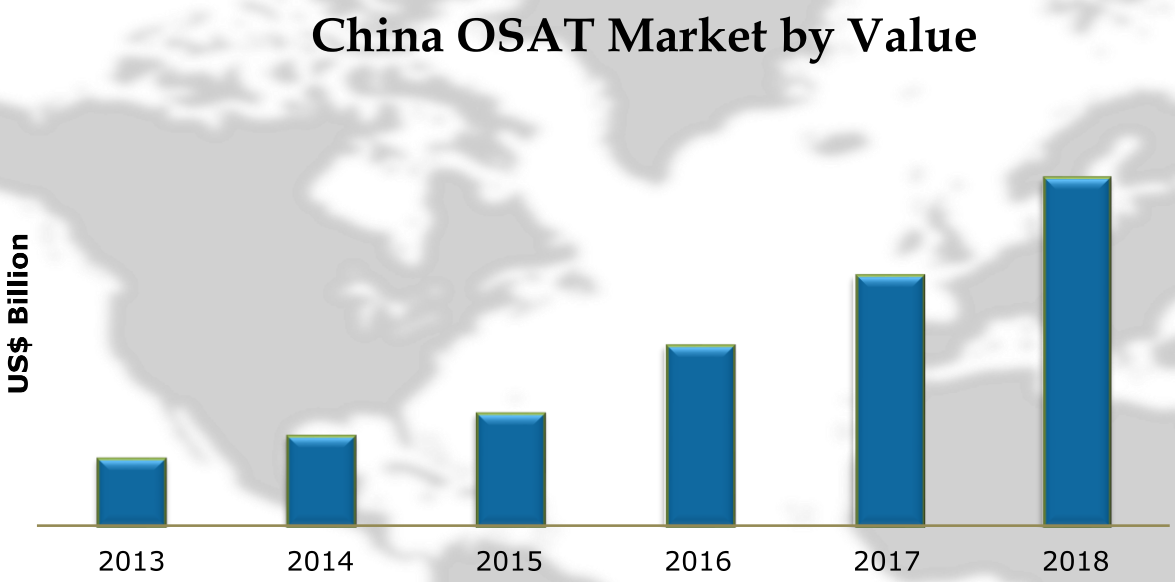
OSAT Market: China Analysis


China OSAT Market by Value

CAGRs	
2013-2018	xx%

OSAT Market: Dynamics

Growth Driver

- Rising Automotive Production
- Rising Internet of Things

Challenges

- Increasing Raw Material Cost
- Volatile demand from cryptocurrency

Market Trends

- Growing Demand for AI-related Semiconductor
- Wafer Level Chip Scale Packaging (WLCSP)Technology

OSAT Market: Competitive Landscape

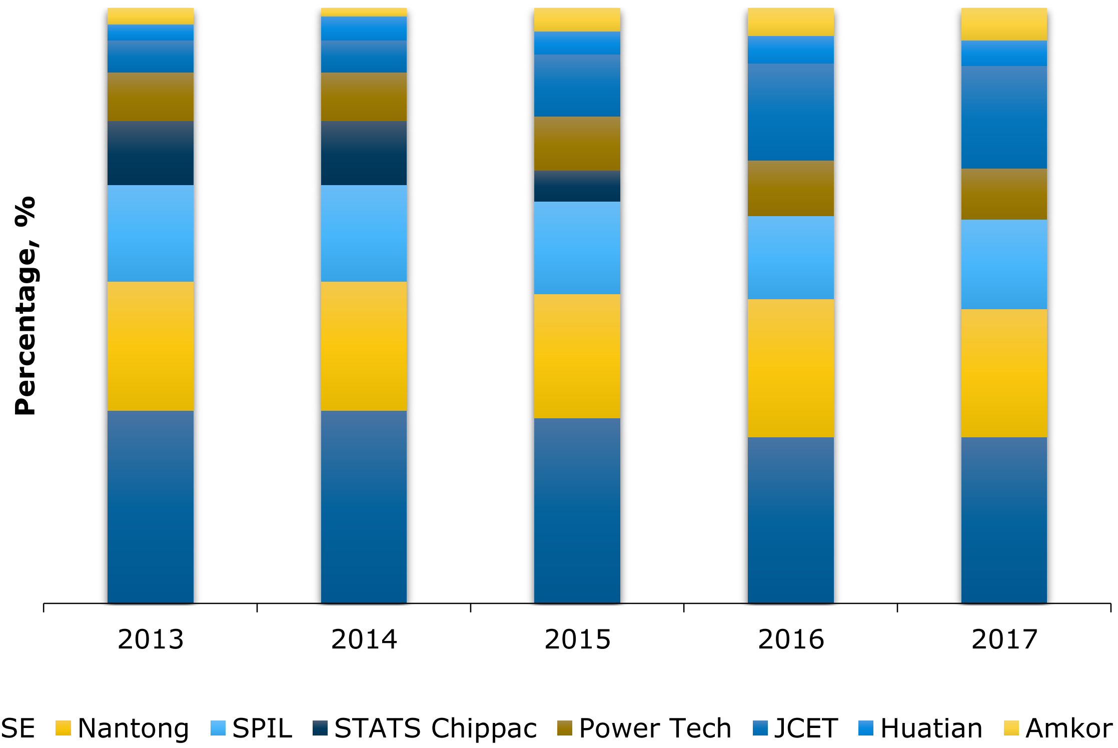
Players Profiled

- Advanced Semiconductor Engineering, (ASE) Inc.

- Amkor Technology, Inc.

- ChipMOS Technologies Inc.

- Mubadala Investment Company (GlobalFoundries Inc.)



Global OSAT Market Players by Share

Note: The graphs on this slide are only for sample representation.

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